ePIC Calorimetry Meeting

Barrel Imaging Calorimeter In-person Workshop

Maria Żurek 05/30/2024



In-person BIC Workshop - May 14-17, 2024

https://indico.bnl.gov/event/22517/timetable/

- Day 1 (overlap with FBTF beam test):
 Updates on ongoing R&D and simulation work
- Day 2: Summary of the status of global, end-of-sector box, and AstroPix module interfaces and work on rev. 1 interfaces documents
- Day 3: Interfaces documentation and detailed PED work planning
- Day 4: Prototypes and test articles planning



Participants

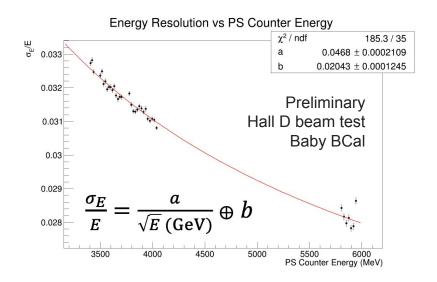
First Name	Last Name	Affiliation	Remote
Akshaya	Vijay	University Of Manitoba	R
Alexander	Bazilevsky	BNL	R
Anthony	Affolder	UC Santa Cruz	R
Aram	Teymurazyan	University of Regina	
Beomkyu	Kim	Sungkyunkwan University	
Blake	Beauchamp	Oklahoma State University	
Bobae	Kim	Argonne National Laboratory	
Chao	Peng	Argonne National Laboratory	
Evan	Van de Wall	Oklahoma State University	
Henry	Klest	Argonne National Laboratory	
Hwi Dong	Yoo	Yonsei University (KR)	
Jared	Richards	Argonne National Laboratory	
Jeongsu	Bok	Pusan National University	
Jessica	Metcalfe	Argonne National Laboratory	
Jonathan	Zarling	University of Regina	

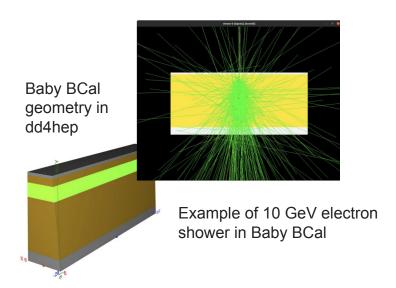
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Kevin	Bailey	Argonne National Laboratory	
KYUNG-WOOK	SHIN	UCSC: SCIPP	
Kyungseon	Joo	UConn	
Manoj	Jadhav	Argonne National Laboratory	
Maria	Zurek	Argonne National Laboratory	
Minho	Kim	Argonne National Laboratory	
Paul E	Reimer	Argonne National Laboratory	
Regina	Caputo	NASA GSFC	
Shin Hyung	Kim	Kyungpook National University	
Sylvester	Joosten	Argonne National Laboratory	
Thomas	O'Connor	Argonne National Laboratory	
Wouter	Deconinck	University of Manitoba	R
Zisis	Papandreou	University of Regina	

28 registered participants

Performance and System Testing

- 1. Update during the BIC in Person Workshop (May 14-17) on electron energy resolution from Hall-D beam test in 2023 and simulations
 - J. Zharling: https://indico.bnl.gov/event/22517/contributions/91532/
 - J. Richards: https://indico.bnl.gov/event/22517/contributions/91533/





Performance and System Testing

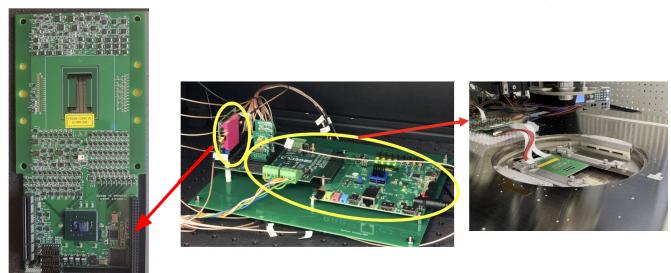
- 2. Update on ongoing beam cosmics test in Fermilab Beam Test Facility (May 8-14) H. Klest, M. Zurek, B. Kim: https://indico.bnl.gov/event/22517/contributions/91530/, https://indico.bnl.gov/event/22517/contributions/91531/, https://indico.bnl.gov/event/22517/contributions/91624/
 - AstroPix and Baby BCal (SciFi/Pb) installed and tested with cosmics in the FBTF
 - Based on performed tests further ongoing efforts to fully readout the Baby BCal (+other FTBF detectors and cosmic paddles) in the same data stream
 - No beam delivered to FBTF so far as of today. Possibility of one week of June 12.
 - Goal:
 - Fully commission the setup with the beam including the first test of the integration between AstroPix and SciFi/Pb.
 - Benchmark response to pions.



Telescope Setup

AstroPix Wafers & Modules

- 1. AstroPix v5 status (to be submitted for an engineering run in June) at the BIC in-person meeting: Nicolas Striebig https://indico.bnl.gov/event/22517/contributions/91071/
 - + Remote session on AstroPix module interfaces with KIT team
- Developments towards wafer testing in Korea:
 - Sanghoon Lim: https://indico.bnl.gov/event/22517/contributions/91072/
 - a. Initial version of AstroPix v3 probe card for the carrier card only expected in a few weeks



Clean Room Hands-on Work

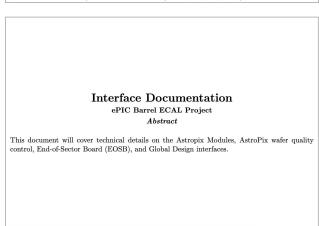
1. Opportunity for a hands-on work on AstroPix Firmware and quad-chip board (Bobae Kim, Amanda Steinhebel, Manoj Jadhav) and SiPM readout board (Henry Klest, Maria Żurek, Aram Teymurazyan)



Sector Design, Mechanics and Integration

- 1. Extensive work on finalizing **revision 1 of the interfaces document for BIC** over the last few months, with a series of topical meetings and writing sessions during the in-person BIC Workshop.
- 2. **Freezing interfaces** as PED funds become available to some of our collaborators will allow teams to **focus on sub-component designs** with clearly defined envelopes and conditions





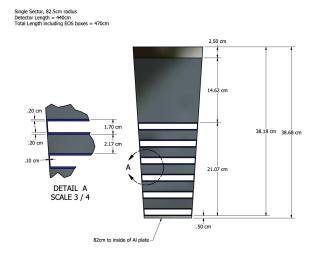


Figure 2: Single Sector, End View. Sectors build of the layers of scintillating fibers embedded in lead shown in gray and 6 slots for AstroPix layers shown in white.

End of Sector Box

1. Finalizing mechanical interfaces for the designs of SiPM and HGCROC PCB, end-of-tray card (AstroPix FPGA), cooling, lightguides, connectors, etc.

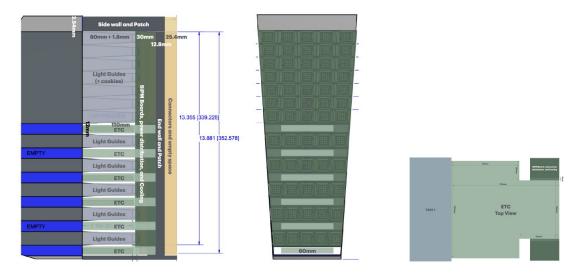


Figure 11: Napkin sketch of the mechanical envelopes for the ESB. Left: Side view in the middle of a sector. Center: Rear view cutout at the SiPM PCB Right: Top view of the AstroPix readout FPGA. TODO: replace with engineering drawings

End of Sector Box (EoSB → ESB)

